

Symbol	Hole Size	Plated	Hole Type	Count	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
□	0.305mm (12.00mil)	PTH	Round	12	Top Layer – Bottom Layer	Via	Rounded	v66h30	Signal via 12mil, 26 mil			–	–
○	0.406mm (16.00mil)	PTH	Round	11	Top Layer – Bottom Layer	Via	Rounded	v81h41	Medium power via, 16 mil, 32 mil			–	–
▽	1.000mm (39.37mil)	PTH	Round	9	Top Layer – Bottom Layer	Pad	(Mixed)	(Mixed)				–	–
☆	2.400mm (94.49mil)	NPTH	Round	4	Top Layer – Bottom Layer	Pad	Rounded	c0hn240				–	–
				36 Total									

Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	0.025mm	4	GTS	
	Top Surface Finish	PbSn	0.020mm			
1	Top Layer	CF-004	0.035mm		GTL	
	Dielectric 1	Core-043	1.499mm	4.3		
2	Bottom Layer	CF-004	0.035mm		GBL	
	Bottom Surface Finish	PbSn	0.020mm			
	Bottom Solder	SM-001	0.025mm	4	GBS	
	Bottom Overlay				GBO	
Total board thickness:			1.659mm			

Client Name: Blues Wireless
Project Name: Mojo 1.1

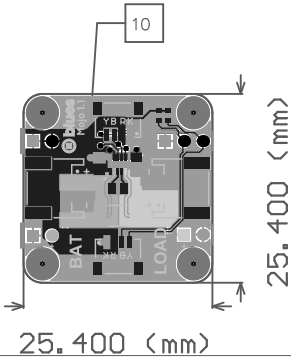
File: Mojo.PcbDoc
Rev: v4

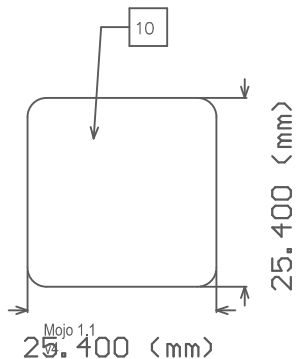
- NOTES:**
UNLESS OTHERWISE SPECIFIED:
- Board Dimension: 25.40mm x 25.40mm
 - Total Thickness: 1.6 mm +/- 10%
 - Board Material: FR-4, Tg130+
 - Copper Layers: 2, Weight: 1 oz
 - Soldermask Layers: Both, Color: Black (LPI preferred)
 - Legend Layers: Both, Color: White. (LPI preferred)
 - Finish: HASL
 - Fabricate PCB According to IPC-6012 Class 1
 - 1.5 mm (0.06") maximum radius on any inside corner.

SPECIAL REQUIREMENTS:
10. A SMD test pad on bottom is normally tented (1 place)

- VENDOR NOTES:**
- Route board shape and any cut outs per Board Outline layer.
 - Place added marking (Job Number, Date Code, Mfg ID, etc) on bottom
 - Boards must pass visual inspection per IPC-A-600 Class 1

Engineering Contact: joseph@toybuilderlabs.com





'Fab Notes'
'Fab Notes'

Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	0.025mm	4	GTS	
	Top Surface Finish	PbSn	0.020mm			
1	Top Layer	CF-004	0.035mm		GTL	
	Dielectric 1	Core-043	1.499mm	4.3		
2	Bottom Layer	CF-004	0.035mm		GBL	
	Bottom Surface Finish	PbSn	0.020mm			
	Bottom Solder	SM-001	0.025mm	4	GBS	
	Bottom Overlay				GBO	
Total board thickness:			1.659mm			

Client Name: Blues Wireless
Project Name: Mojo 1.1

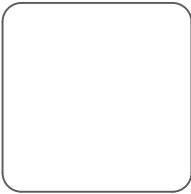
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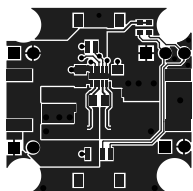
- NOTES:**
UNLESS OTHERWISE SPECIFIED:
- 1. Board Dimension: 25.40mm x 25.40mm
 - 2. Total Thickness: 1.6 mm +/- 10%
 - 3. Board Material: FR-4, Tg130+
 - 4. Copper Layers: 2, Weight: 1 oz
 - 5. Soldermask Layers: Both, Color: Black (LPI preferred)
 - 6. Legend Layers: Both, Color: White. (LPI preferred)
 - 7. Finish: HASL
 - 8. Fabricate PCB According to IPC-6012 Class 1
 - 9. 1.5 mm (0.06") maximum radius on any inside corner.

SPECIAL REQUIREMENTS:
10. A SMD test pad on bottom is normally tented (1 place)

VENDOR NOTES:
11. Route board shape and any cut outs per Board Outline layer.
12. Place added marking (Job Number, Date Code, Mfg ID, etc) on bottom
13. Boards must pass visual inspection per IPC-A-600 Class 1

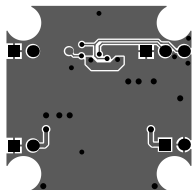
Engineering Contact: joseph@toybuilderlabs.com





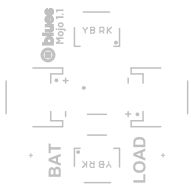
Mojo 1.1
v4

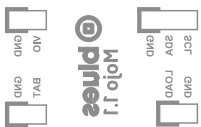
'Top Layer'
'Top Layer'

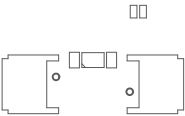


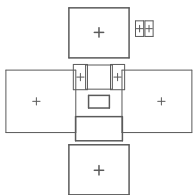
Mojo 1.1
v4

'Bottom Layer'
'Bottom Layer'









Mojo 1.1
v4

'Top Courtyard'
'Top Courtyard'

Symbol	Hole Size	Plated	Hole Type	Count	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
□	0.305mm (12.00mil)	PTH	Round	12	Top Layer - Bottom Layer	Via	Rounded	v66h30	Signal via 12mil, 26 mil			-	-
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▽	1.000mm (39.37mil)	PTH	Round	9	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
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				36 Total									

